

## KLT-E6K-IMX214 V2.0

### 13MP Sony IMX214 MIPI Interface M12 Fixed Focus Camera Module



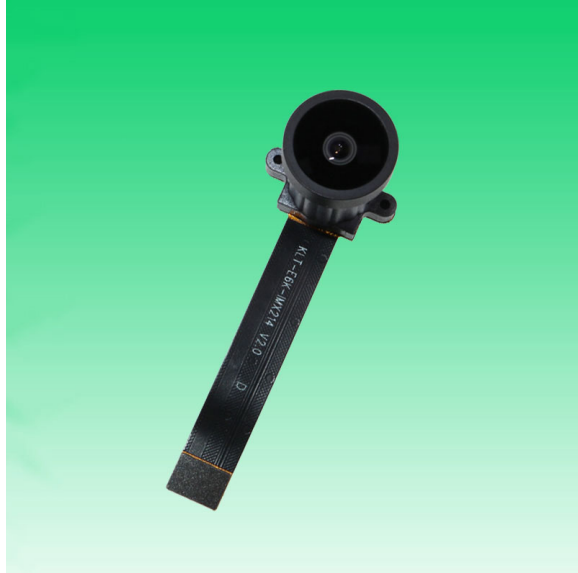
Front View



Back View

#### Specifications

<b>Camera Module No.</b>	<b>KLT-E6K-IMX214 V2.0</b>
<b>Resolution</b>	13MP
<b>Image Sensor</b>	IMX214
<b>Sensor Type</b>	1/3.06"
<b>Pixel Size</b>	1.12 um x 1.12 um
<b>EFL</b>	2.27 mm
<b>F.NO</b>	2.40
<b>Pixel</b>	4224 x 3136
<b>View Angle</b>	152.0°(DFOV) 122.0°(HFOV) 93.0°(VFOV)
<b>Lens Dimensions</b>	13.00 x 13.00 x 22.82 mm
<b>Module Size</b>	60.00 x 22.00 mm
<b>Module Type</b>	Fixed Focus
<b>Interface</b>	MIPI
<b>Auto Focus VCM Driver IC</b>	None
<b>Lens Model</b>	KLT-LENS-YM6081
<b>Lens Type</b>	650nm IR Cut
<b>Operating Temperature</b>	-20°C to +70°C
<b>Mating Connector</b>	DF30FC-30DS-0.4V

**KLT-E6K-IMX214 V2.0****13MP Sony IMX214 MIPI Interface M12 Fixed Focus Camera Module**

Top View



Side View



Bottom View

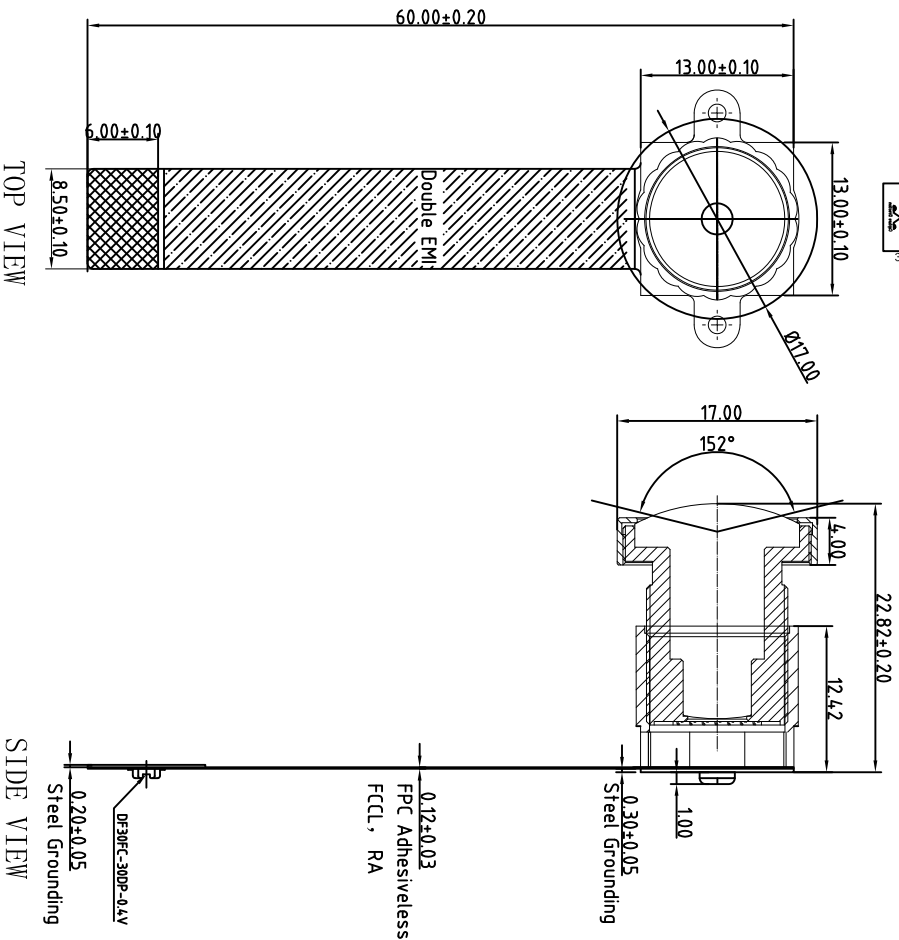


Mating Connector

# ROHS

## PIN SIGNAL

1	NC
2	NC
3	DVDD1.2V
4	DOVDD1.8V
5	NC
6	AGND
7	AVDD2.8V
8	DGND
9	SDA
10	SCL
11	RST
12	PWDN
13	GND
14	MCLK
15	GND
16	MDP3
17	MDN3
18	GND
19	MDP2
20	MDN2
21	GND
22	MDP1
23	MDN1
24	GND
25	MCP
26	MCN
27	GND
28	MDP0
29	MDN0
30	GND



NOTE: BOTTEM VIEW  
 1.The device slave address:0x20(w);0x21(r)

### Parameters:

#### 1、 Sensor specification:

Image Sensor: IMX214  
 Pixel: 1.12um×1.12um  
 Lens Type: 1/3.06  
 Important Voltage Description: DVDD1.2V (external power supply);

#### 2、 Lens specification:

FOV: 152°(D), 122°(H), 93°(V)  
 F/NO.: 2.4  
 TV distortion: <- 15%  
 Focal length: 2.27mm  
 Composition: 6G+IR FILTER  
 IR Cut Coating: 650nm±10nm@50%

## Kai Lap Technologies Group Ltd

Designed By	Kevin	Model Name:	KLT-E6K-IMX214 V2.0		
Checked By	Aouly Yan	Projection Type:	Third Angle	Unit:	mm
		Scale:	1:1	Sheet:	1 of 1
		Version:	1/0		

Version Mark	Information	Date
V1.0	PD First Version	2017-03-16
V2.0	Change lens and holder	2017-10-26



Lens Model: KLT-LENS-YM6081

No.	ITEM	SPECIFICATION
1	孔径 (EFL)	2.25mm
2	光学后焦 (BFL)	3.73mm (IR0.21mm)
3	机械后焦 (MFL)	3.2mm (IR0.21mm)
4	光学总长 (TTL)	22mm (IR0.21mm)
5	光量 (FNo)	2.8
6	最大像面/机械像面 (C/Co)	Φ5.0
7	光学材料 (Structure)	6S+IR
8	接口 (Mount)	M12-P0.5
9	光谱透射率 (Special Transmittar)	Trans=90%
Sensor		
IMX214		
10	视场角 (FOV)	Vertical
		Horizontal
		Diagonal
11	光学畸变 (Optical Distortion)	-4.3%
12	相对亮度 (Relative I)	65.3%
13	主光线角度 (CRA)	29.7°
14	R FILTER SPEC: Built-in Other's raw area	
T-ray>=8% @ 420-650 nm T-ray>=8% @ 570-1100 nm T-ray>=3% @ 700-1000 nm T-CO @ 1050 nm		

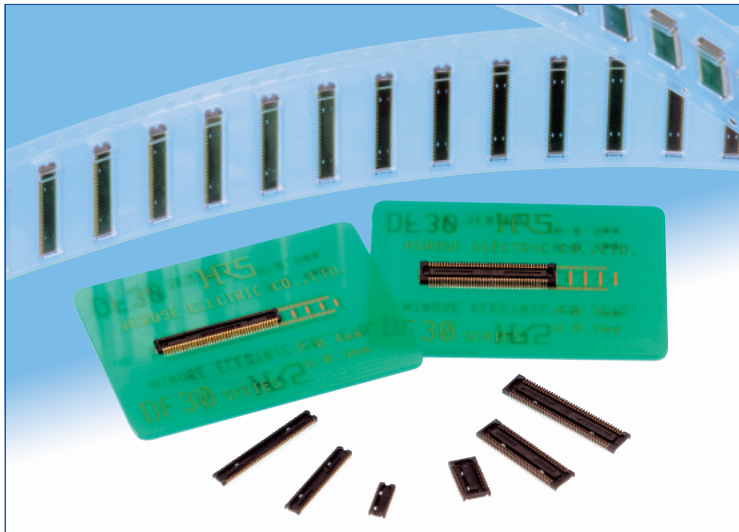
设计	处数	分区	更改文件号	签名	年、月、日
审核		20210427	标准化		
工艺			批准		

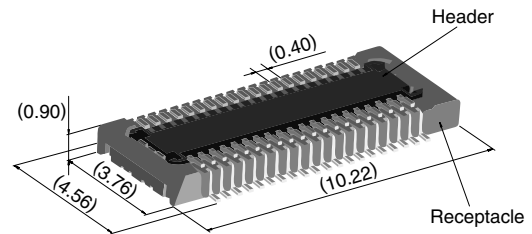
阶段标记	重量	比例
		4:1
共	张	第
		张

# 0.4 mm Pitch, 0.9 mm Height, Board-to-Board / Board-to-FPC Connectors

## DF30 Series



### Extremely small size



40 positions shown

### Overview

Continuous miniaturization and increased component density on PCB created demand for extremely low profile connectors. This series is addition of a new extremely low profile connectors to Hirose's wide range of high reliability board-to-board/board-to-FPC connection solutions.

### Features

#### 1. Contact reliability

Concentration of the contact's normal forces at the single point assures good contact wipe and electrical reliability, while confirming the fully mated condition with a definite tactile click.

#### 2. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces the connectors will self align in horizontal axis within 0.3 mm.

#### 3. Automatic board placement

Packaged on tape-and-reel the plug and headers have sufficiently large flat areas to allow pick-up with vacuum nozzles of automatic placement equipment.

#### 4. Variety of contact positions and styles

Available in standard contact positions of: 20, 22, 24, 30, 34, 40, 50, 60, 70 and 80 with and without metal fittings. Addition of metal fittings does not affect external dimensions of the connectors.

Smaller contact positions are also available.

#### 5. Support for continuity test connector

Connectors which have increased insertion and removal durability are available for continuity tests. Contact your Hirose sales representative for details.

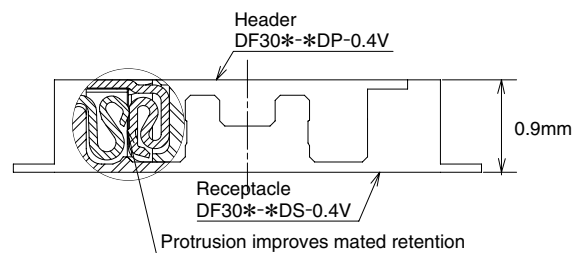
### Applications

Cellular phones, PDA's, mobile computers, digital cameras, digital video cameras, and other devices demanding high reliability connections in extremely limited spaces.

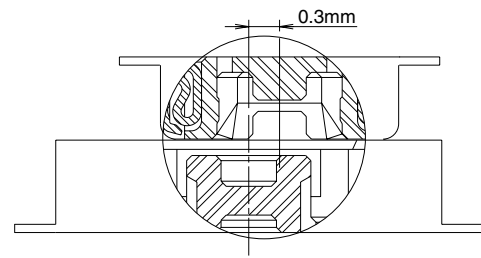
#### Low profile

#### Increased mated retention

#### High contact reliability



### Self alignment



## Product Specifications

Rating	Rated current 0.3A	Operating temperature range : -35°C to 85°C (Note 1)	Storage temperature range -10°C to 60°C (Note 2)
	Rated voltage 30V AC	Operating humidity range : Relative humidity 20% to 80%	Storage humidity range Relative humidity 40% to 70% (Note 2)

Item	Specification	Conditions
1. Insulation resistance	50 MΩ min.	100V DC
2. Withstanding voltage	No flashover or insulation breakdown.	100V AC / one minute
3. Contact resistance	100 mΩ max.	100 mA
4. Vibration	No electrical discontinuity of 1 μs or more	Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 2 hours, 3 axis
5. Humidity	Contact resistance: 100 mΩ max. Insulation resistance: 25 MΩ min.	96 hours at temperature of 40°C±2°C and RH of 90% to 95%
6. Temperature cycle	Contact resistance: 100 mΩ max. Insulation resistance: 50 MΩ min.	Temperature: -55°C→+5°C to +35°C→+85°C→+5°C to +35°C Duration: 30→10→30→10(Minutes) 5 cycles
7. Durability (insertions/withdrawals)	Contact resistance: 100 mΩ max.	50 cycles(Connector for conductivity tests: 500 cycles)
8. Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 300°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating temperature range and humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

## Materials and Finishes

Connectors	Component	Material	Finish	Remarks
Receptacles and Headers	Insulator	LCP	Color : Black	UL94V-0
	Contacts	Phosphor bronze	Gold plated	————
	Metal fittings	Phosphor bronze	Tin-copper plated	————

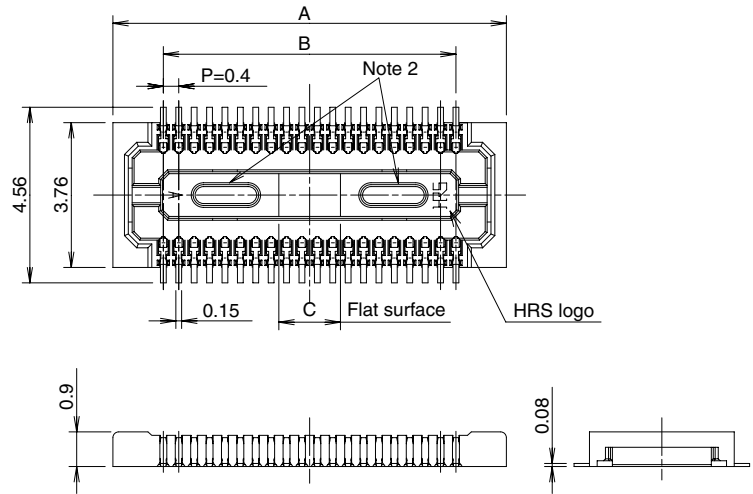
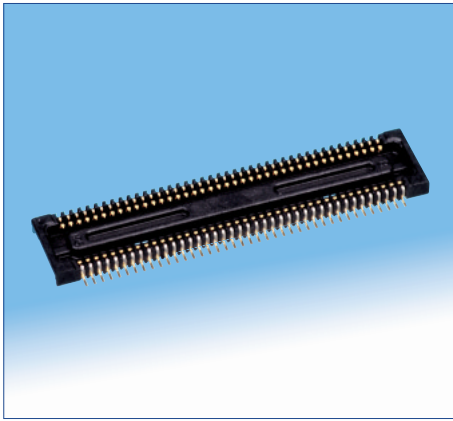
## Ordering information

### Receptacles and Headers

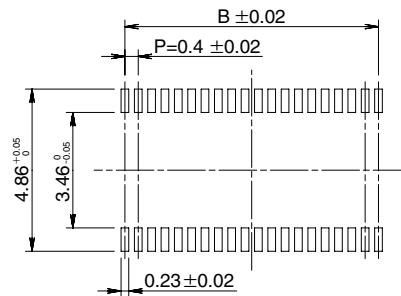
**DF30**   **FC** -   **\***   **DS - 0.4**   **V**   **(\*\*)**  
1   2   3   4   5   6   7

<b>1</b> Series name: DF30	<b>5</b> Contact pitch: 0.4 mm
<b>2</b> Configuration FB: With metal fittings, without bosses FC: Without metal fittings, without bosses CJ: Connector for conductivity tests	<b>6</b> Termination section V: Straight SMT
<b>3</b> Number of positions: 20, 22, 24, 30, 34, 40, 50, 60, 70, 80	<b>7</b> Packaging (81): Embossed tape packaging (5,000 pieces per reel) (82): Embossed tape packaging (1,000 pieces per reel)
<b>4</b> Connector type DS: Double row receptacle DP: Double row header	

## ■ Receptacles (without metal fittings)



## ◆ Recommended PCB mounting pattern



Recommended solder paste thickness: 120  $\mu\text{m}$

[Specification number] -\*\*, (\*\*)

(81): Embossed tape packaging (5,000 pieces per reel)

\* Tolerances non- accumulative.

Unit: mm

Part Number	CL No.	Number of contacts	A	B	C
DF30FC-20DS-0.4V(**)	CL684-1109-8-**	20	6.22	3.6	1.2
DF30FC-22DS-0.4V(**)	CL684-1110-7-**	22	6.62	4.0	1.2
DF30FC-24DS-0.4V(**)	CL684-1111-0-**	24	7.02	4.4	1.2
DF30FC-30DS-0.4V(**)	CL684-1112-2-**	30	8.22	5.6	1.2
DF30FC-34DS-0.4V(**)	CL684-1113-5-**	34	9.02	6.4	1.36
DF30FC-40DS-0.4V(**)	CL684-1078-6-**	40	10.22	7.6	1.6
DF30FC-50DS-0.4V(**)	CL684-1114-8-**	50	12.22	9.6	2.0
DF30FC-60DS-0.4V(**)	CL684-1082-3-**	60	14.22	11.6	2.4
DF30FC-70DS-0.4V(**)	CL684-1115-0-**	70	16.22	13.6	2.8
DF30FC-80DS-0.4V(**)	CL684-1116-3-**	80	18.22	15.6	3.2

Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.

## [Product Brief]

Ver.1.0

# IMX214

### Diagonal 5.867mm (Type 1/3.06) 13M Pixel CMOS Image Sensor with Square Pixel for Color Cameras

---

#### Description

IMX214 is a diagonal 5.867mm(Type 1/3.06) 13M pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RS™ technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spacially varying exposure technology, high dynamic range still pictures and movies are achievable. It equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.0V and 1.8 V for input/output interface and achieves low power consumption. IMX214 is designed for use in cellular phones or tablet devices\*.

---

#### Functions and Features

- ◆ Back illuminated and stacked CMOS image sensor Exmor RS
- ◆ Single Frame High Dynamic Range (HDR) with equivalent full pixels.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR).4K2K @30fps (Normal / HDR)1080p @60fps (Normal / HDR)
- ◆ Output video format of RAW10/8, COMP8/6
- ◆ Pixel binning readout and H/V sub sampling function
- ◆ Advanced Noise Reduction (Chroma noise reduction and luminance noise reduction)
- ◆ Independent flipping and mirroring.
- ◆ CSI 2 serial data output (MIPI 2lane/4lane, Max. 1.2Gbps/lane, DPHY spec. ver. 1.1 compliant)
- ◆ 2wire serial communication
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Advanced Noise Reduction.
- ◆ Dynamic Defect Pixel Correction.
- ◆ Zero shutter lag.
- ◆ Power on reset function
- ◆ Dual sensor synchronization operation.
- ◆ 8K bit of OTP ROM for users.
- ◆ Built in temperature sensor

#### NOTE)

1. When using this product for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and Tablet PCs. Consult your Sony sales representative if you have any questions.



## Device Structure

◆ CMOS image sensor	
◆ Image size	: Diagonal 5.867mm (Type 1/3.06)
◆ Total number of pixels	: 4224 (H) × 3200(V) approx. 13.51M pixels
◆ Number of effective pixels	: 4224 (H) × 3136 (V) approx. 13.25 M pixels
◆ Number of active pixels	: 4208 (H) × 3120 (V) approx. 13.13 M pixels
◆ Chip size	: 6.100mm (H) × 4.524mm (V)
◆ Unit cell size	: 1.12 μm (H) × 1.12 μm (V)
◆ Substrate material	: Silicon

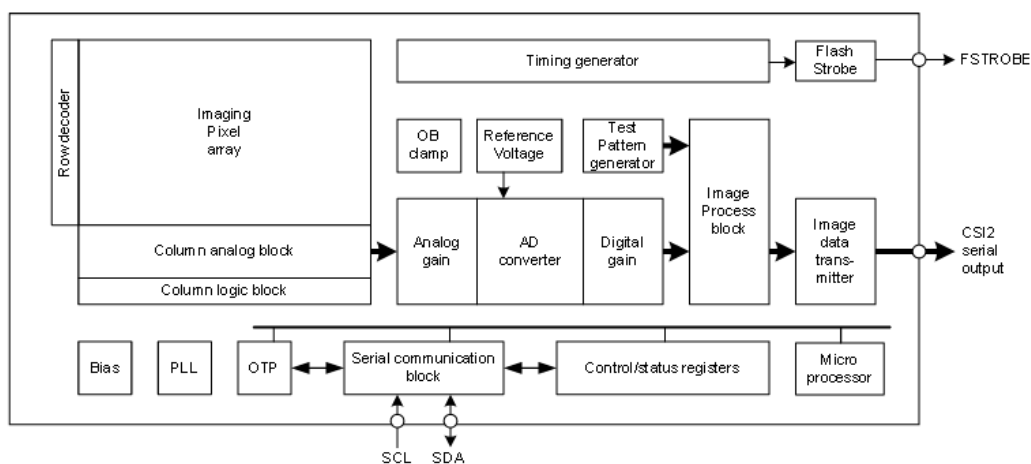
## Functional Description

### System Outline

IMX214 is a CMOS active pixel type image sensor which adopts the Exmor RS™ technology to achieve high sensitivity, low noise and high speed image capturing. It is embedded with backside illuminated imaging pixel, low noise analog amplifier, column parallel A/D converters which enables high speed capturing, digital amplifier, image binning circuit, timing control circuit for imaging size and frame rate, CSI2 image data high speed serial interface, PLL oscillator, and serial communication interface to control these functions.

Several additional image processing functions and peripheral circuits are also included for easy system optimization by the users. A one time programmable memory is embedded in the chip for storing the user data. It has 8 K-bit for users, 10 K-bit as a whole.

### Block Diagram



## Exmor RS

\* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.

Sony reserves the right to change products and specifications without prior notice.

This information does not convey any license by any implication or otherwise under any patents or other right.

Application circuits shown, if any, are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits.



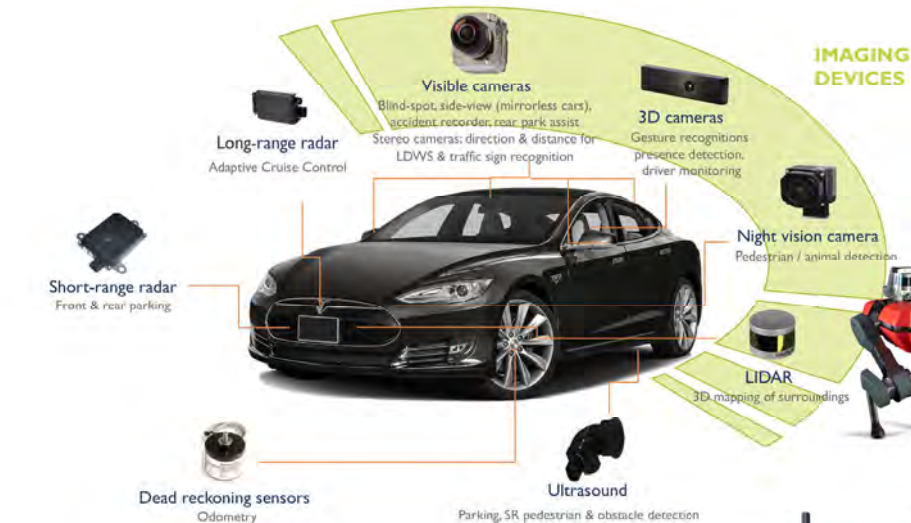
## Camera Module Pinout Definition Reference Chart

OmniVision	Sony	Samsung	On-Semi	Aptina	Himax	GalaxyCore	PixArt	SmartSens	Sensors	
Pin Signal										
Description										
DGND	GND									ground for digital circuit
AGND										ground for analog circuit
PCLK	DCK									DVP PCLK output
XCLR	PWDN	XSHUTDOWN	STANDBY							power down active high with internal pull-down resistor
MCLK	XVCLK	XCLK	INCK							system input clock
RESET	RST									reset active low with internal pull-up resistor
NC	NULL									no connect
SDA	SIO_D	SIOD								SCCB data
SCL	SIO_C	SIOC								SCCB input clock
VSYNC	XVS	FSYNC								DVP VSYNC output
HREF	XHS									DVP HREF output
DOVDD										power for I/O circuit
AFVDD										power for VCM circuit
AVDD										power for analog circuit
DVDD										power for digital circuit
STROBE	FSTROBE									strobe output
FSIN										synchronize the VSYNC signal from the other sensor
SID										SCCB last bit ID input
ILPWM										mechanical shutter output indicator
FREX										frame exposure / mechanical shutter
GPIO										general purpose inputs
SLASEL										I2C slave address select
AFEN										CEN chip enable active high on VCM driver IC
<b>MIPI Interface</b>										
MDN0	DN0	MD0N	DATA_N	DMO1N						MIPI 1st data lane negative output
MDP0	DP0	MD0P	DATA_P	DMO1P						MIPI 1st data lane positive output
MDN1	DN1	MD1N	DATA2_N	DMO2N						MIPI 2nd data lane negative output
MDP1	DP1	MD1P	DATA2_P	DMO2P						MIPI 2nd data lane positive output
MDN2	DN2	MD2N	DATA3_N	DMO3N						MIPI 3rd data lane negative output
MDP2	DP2	MD2P	DATA3_P	DMO3P						MIPI 3rd data lane positive output
MDN3	DN3	MD3N	DATA4_N	DMO4N						MIPI 4th data lane negative output
MDP3	DP3	MD3P	DATA4_P	DMO4P						MIPI 4th data lane positive output
MCN	CLKN	CLK_N	DCKN							MIPI clock negative output
MCP	CLKP	MCP	CLK_P	DCKN						MIPI clock positive output
<b>DVP Parallel Interface</b>										
D0	DO0	Y0								DVP data output port 0
D1	DO1	Y1								DVP data output port 1
D2	DO2	Y2								DVP data output port 2
D3	DO3	Y3								DVP data output port 3
D4	DO4	Y4								DVP data output port 4
D5	DO5	Y5								DVP data output port 5
D6	DO6	Y6								DVP data output port 6
D7	DO7	Y7								DVP data output port 7
D8	DO8	Y8								DVP data output port 8
D9	DO9	Y9								DVP data output port 9
D10	DO10	Y10								DVP data output port 10
D11	DO11	Y11								DVP data output port 11



your **BEST** camera module partner

## Cameras Applications





## Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



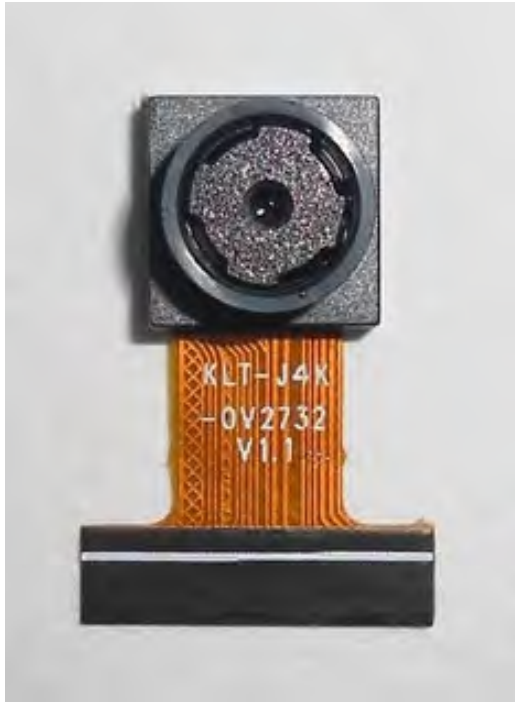


Inspection Item		Inspection Method	Standard of Inspection		
Category	Item				
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
	Function	Image	No Communication	Test Board	Not Allowed
			Bright Pixel	Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center	
Blurry			The Naked Eye	Not Allowed	
No Image			The Naked Eye	Not Allowed	
Vertical Line			The Naked Eye	Not Allowed	
Horizontal Line			The Naked Eye	Not Allowed	
Light Leakage			The Naked Eye	Not Allowed	
Blinking Image			The Naked Eye	Not Allowed	
Bruise			Inspection Jig	Not Allowed	
Resolution			Chart	Follows Outgoing Inspection Chart Standard	
Color			The Naked Eye	No Issue	
Noise			The Naked Eye	Not Allowed	
Corner Dark			The Naked Eye	Less Than 100px By 100px	
Color Resolution			The Naked Eye	No Issue	
Dimension	Height	The Naked Eye	Follows Approval Data Sheet		
	Width	The Naked Eye	Follows Approval Data Sheet		
	Length	The Naked Eye	Follows Approval Data Sheet		
	Overall	The Naked Eye	Follows Approval Data Sheet		



## KLT Package Solutions

KLT Camera Module



Complete with Lens Protection Film



Tray with Grid and Space



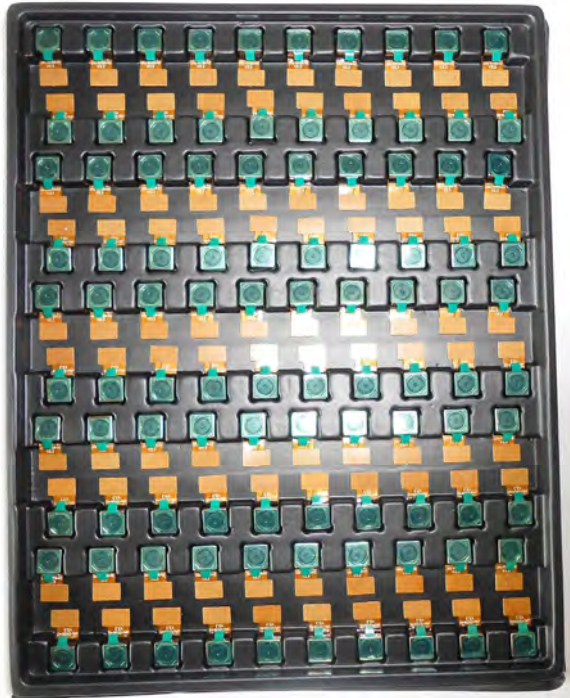
Place Cameras on the Tray





## Camera Modules Package Solution

Full Tray of Cameras



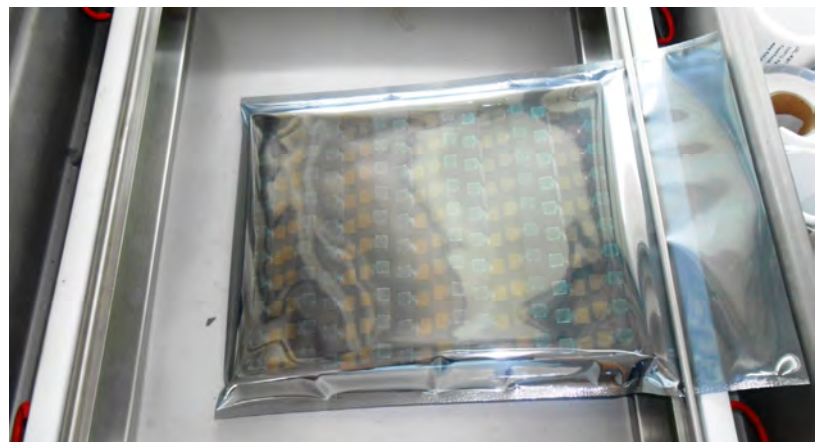
Cover Tray with Lid



Put Tray into Anti-Static Bag



Vacuum the Anti-Static Bag





## Camera Modules Package Solution

Sealed Vacuum Bag with Labels

1. Model and Description 2. Quantity 3. Shipping Date 4. Caution







## Large Order Package Solution

Place Foam Sheets Between Trays

Foam Sheets are Slightly Larger than Trays



Place Foam Sheets and Trays into Box

Foam Sheets are Tightly Fitting Box





## Small Order Package Solution

Place Foam Sheets and Trays into Small Box



Foam Sheets are Nicely Fitting the Small Box



Package in Small Box for Shipment



Place Small Boxes into Larger Box





*your BEST camera module partner*

## Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box



### Carbon Box Ready for Shipment

1. Delivery Address and Phone No. 2. Box No. and Ship Date 3. Fragile Caution





## Sample Order Package Solution

Place Sample into Small Anti-Static Bag



Place Connectors into Small Ant-Static Bag



### Sample Labels on the Small Bag

1. Camera Module or Connector Model 2. Shipping Date and Quantity 3. Caution





## Connectors Large Order Package Solution

Connectors in a Wheel



Label Connectors in the Wheel



The Wheel is Perfectly Fitting the Box



Connectors Box Ready for Shipment



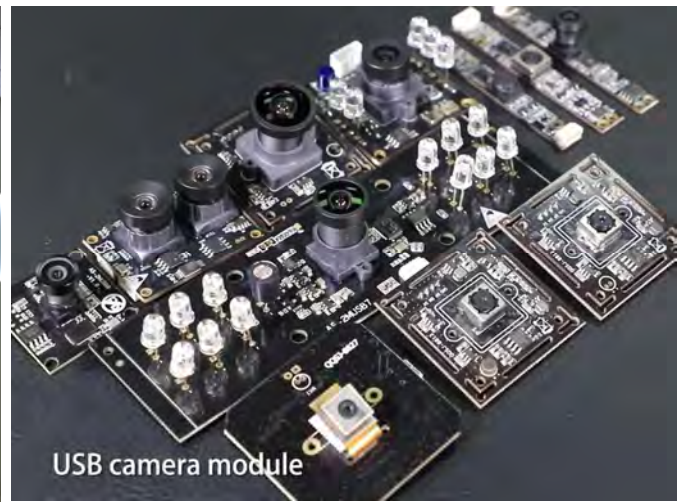


## Company Kai Lap Technologies (KLT)

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



## Limited Warranty

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, [www.KaiLapTech.com](http://www.KaiLapTech.com). Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequent events.





# CMOS CAMERA MODULES



*your BEST camera module partner*

## KLT Strength

### Powerful Factory



### Professional Service



### Promised Delivery



[www.KaiLapTech.com](http://www.KaiLapTech.com) [sales@KaiLapTech.com](mailto:sales@KaiLapTech.com) Tel: (852) 6908 1256 Fax: (852) 3017 6778

All rights reserved @ Kai Lap Technologies Group Ltd. Specifications subject to change without notice.